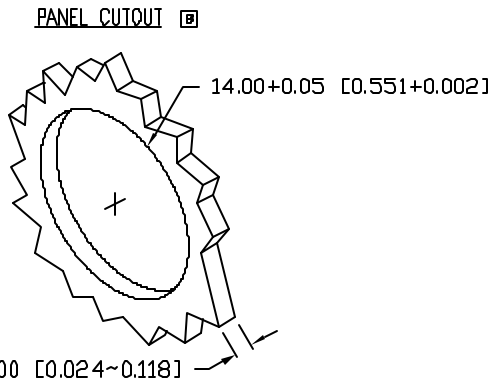
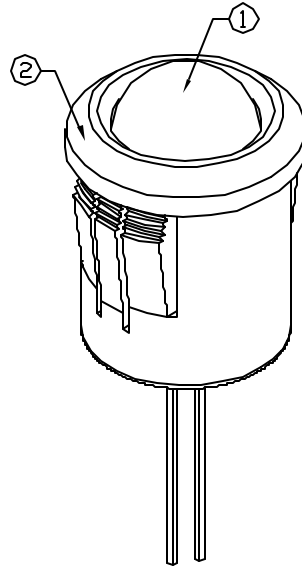
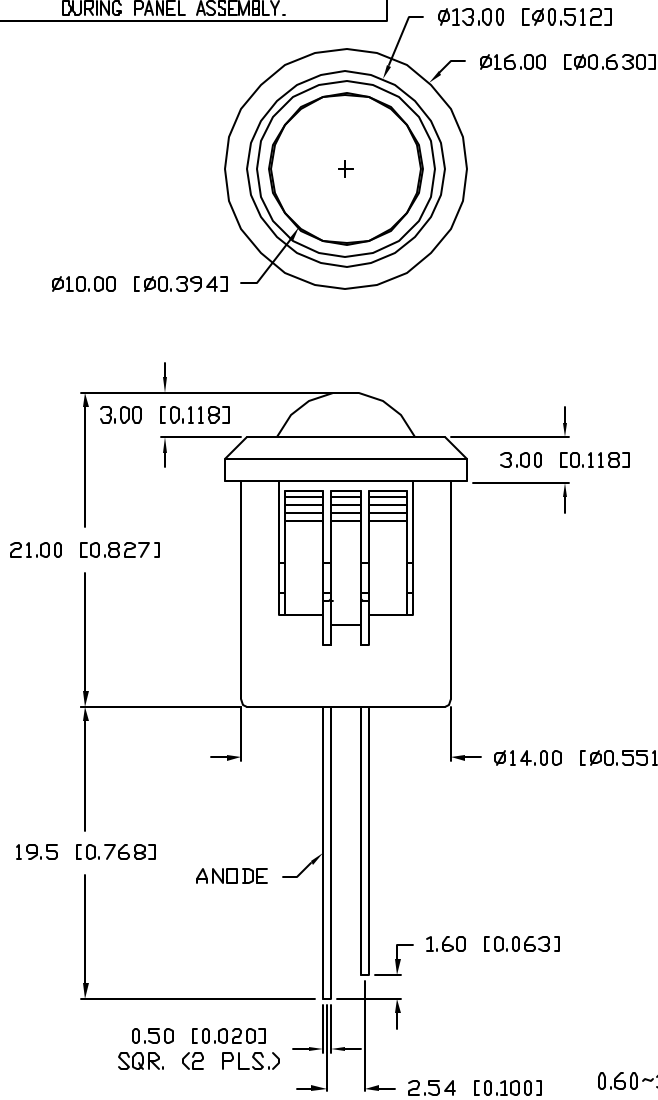


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CAUTION: PRESSURE SENSITIVE ASSEMBLY
AVOID APPLYING PRESSURE TO LED
DURING PANEL ASSEMBLY.



PART NUMBER
SSI-LXH1090SRD

REV.
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10112 & #10113.	4.18.96
B	E.C.N. #10539.	3.9.00
C	E.C.N. #10BRDR. & REDRAWN IN 3D.	1.5.02

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	V_f	
REVERSE VOLTAGE	4.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		80		mcad	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

- SSL-LX100133SRD LED.
- SSH-RTF1090 HOLDER.
- UV EPOXY TO RETAIN LED IN HOLDER.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= ± 1 (± 0.039), XX= ± 0.5 (± 0.020), XXX= ± 0.25 (± 0.010), XXXX= ± 0.127 (± 0.005). LEAD SIZE= ± 0.05 (± 0.002), LEAD LENGTH= ± 0.75 (± 0.030), MIN= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$ DECIMAL PRECISION, MAX= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$ DECIMAL PRECISION

REV. C PART NUMBER SSI-LXH1090SRD

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290 E. HELEN ROAD
PALATINE, IL 60067-6976
PHONE: +1.847.359.2790
US WEB: www.lumex.com
TW WEB: www.lumex.com.tw

T-10mm 660nm SUPER RED LED PANEL INDICATOR,
RED DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC CHECKED BY: APPROVED BY: DATE: 7.14.93
PAGE: 1 OF 1
SCALE: N/A